74LVC8T245; 74LVCH8T245

8-bit dual supply translating transceiver; 3-state

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Pro

Product data sheet

General description 1.

The 74LVC8T245; 74LVCH8T245 are 8-bit dual supply translating transceivers with 3-state outputs that enable bidirectional level translation. They feature two data input-output ports (pins An and Bn), a direction control input (DIR), an output enable input (OE) and dual supply pins ($V_{CC(A)}$ and $V_{CC(B)}$). Both $V_{CC(A)}$ and $V_{CC(B)}$ can be supplied at any voltage between 1.2 V and 5.5 V making the device suitable for translating between any of the low voltage nodes (1.2 V, 1.5 V, 1.8 V, 2.5 V, 3.3 V and 5.0 V). Pins An, OE and DIR are referenced to V_{CC(A)} and pins Bn are referenced to V_{CC(B)}. A HIGH on DIR allows transmission from An to Bn and a LOW on DIR allows transmission from Bn to An. The output enable input (OE) can be used to disable the outputs so the buses are effectively isolated.

The devices are fully specified for partial power-down applications using I_{OFF}. The I_{OFF} circuitry disables the output, preventing any damaging backflow current through the device when it is powered down. In suspend mode when either $V_{\text{CC(A)}}$ or $V_{\text{CC(B)}}$ are at GND level, both A port and B port are in the high-impedance OFF-state.

Active bus hold circuitry in the 74LVCH8T245 holds unused or floating data inputs at a valid logic level.

2. Features and benefits

- Wide supply voltage range:
 - V_{CC(A)}: 1.2 V to 5.5 V
 - ◆ V_{CC(B)}: 1.2 V to 5.5 V
- High noise immunity
- Complies with JEDEC standards:
 - ◆ JESD8-7 (1.2 V to 1.95 V)
 - JESD8-5 (1.8 V to 2.7 V)
 - JESD8C (2.7 V to 3.6 V)
 - ◆ JESD36 (4.5 V to 5.5 V)
- ESD protection:
 - HBM JESD22-A114F Class 3A exceeds 4000 V
 - MM JESD22-A115-B exceeds 200 V
 - CDM JESD22-C101E exceeds 1000 V
- Maximum data rates:
 - ◆ 420 Mbps (3.3 V to 5.0 V translation)
 - 210 Mbps (translate to 3.3 V))
 - 140 Mbps (translate to 2.5 V)
 - 75 Mbps (translate to 1.8 V)



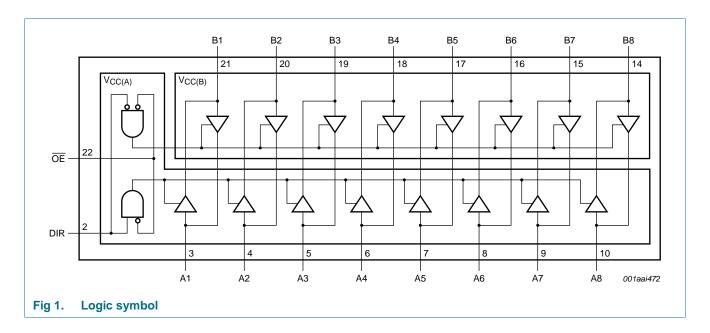
- ◆ 60 Mbps (translate to 1.5 V)
- Suspend mode
- Latch-up performance exceeds 100 mA per JESD 78B Class II
- \pm 24 mA output drive (V_{CC} = 3.0 V)
- Inputs accept voltages up to 5.5 V
- Low power consumption: 30 μA maximum I_{CC}
- I_{OFF} circuitry provides partial Power-down mode operation
- Multiple package options
- Specified from -40 °C to +85 °C and -40 °C to +125 °C

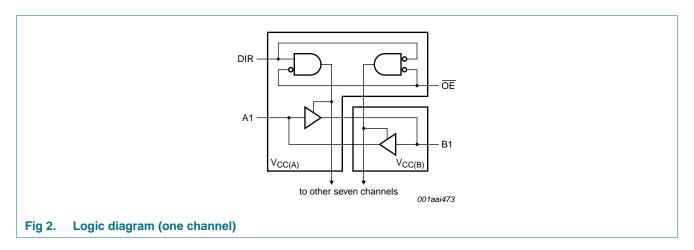
3. Ordering information

Table 1. Ordering information

| Type number | Package | | | | | | | |
|---------------|-------------------|----------|--|----------|--|--|--|--|
| | Temperature range | Name | Description | Version | | | | |
| 74LVC8T245PW | -40 °C to +125 °C | TSSOP24 | plastic thin shrink small outline package; 24 leads; | SOT355-1 | | | | |
| 74LVCH8T245PW | | | body width 4.4 mm | | | | | |
| 74LVC8T245BQ | –40 °C to +125 °C | DHVQFN24 | p | SOT815-1 | | | | |
| 74LVCH8T245BQ | _ | | thin quad flat package; no leads; 24 terminals; body $3.5 \times 5.5 \times 0.85$ mm | | | | | |

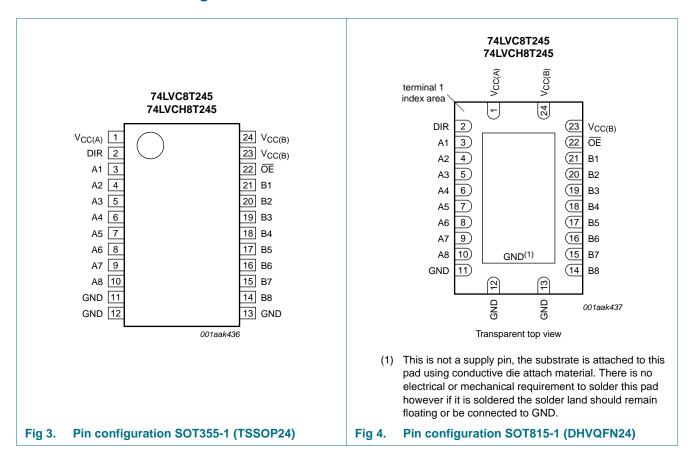
4. Functional diagram





5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

| Symbol | Pin | Description |
|--------------------|--------------------------------|--|
| $V_{CC(A)}$ | 1 | supply voltage A (An inputs/outputs, $\overline{\text{OE}}$ and DIR inputs are referenced to $V_{\text{CC(A)}})$ |
| DIR | 2 | direction control |
| A1 to A8 | 3, 4, 5, 6, 7, 8, 9, 10 | data input or output |
| GND[1] | 11 | ground (0 V) |
| GND[1] | 12 | ground (0 V) |
| GND[1] | 13 | ground (0 V) |
| B1 to B8 | 21, 20, 19, 18, 17, 16, 15, 14 | data input or output |
| ŌĒ | 22 | output enable input (active LOW) |
| V _{CC(B)} | 23 | supply voltage B (Bn inputs/outputs are referenced to V _{CC(B)}) |
| $V_{CC(B)}$ | 24 | supply voltage B (Bn inputs/outputs are referenced to V _{CC(B)}) |

^[1] All GND pins must be connected to ground (0 V).

6. Functional description

Table 3. Function table [1]

| Supply voltage | Input | Input | | Input/output ^[3] | | |
|---|-------|--------------------|---------|-----------------------------|--|--|
| V _{CC(A)} , V _{CC(B)} | OE[2] | DIR ^[2] | An[2] | Bn[2] | | |
| 1.2 V to 5.5 V | L | L | An = Bn | input | | |
| 1.2 V to 5.5 V | L | Н | input | Bn = An | | |
| 1.2 V to 5.5 V | Н | Χ | Z | Z | | |
| GND[3] | X | Х | Z | Z | | |

^[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------------|-------------------------|---|-----------------|-----------------|------|
| $V_{CC(A)}$ | supply voltage A | | -0.5 | +6.5 | V |
| $V_{CC(B)}$ | supply voltage B | | -0.5 | +6.5 | V |
| I _{IK} | input clamping current | V _I < 0 V | -50 | - | mA |
| V_{I} | input voltage | | <u>[1]</u> –0.5 | +6.5 | V |
| I _{OK} | output clamping current | V _O < 0 V | -50 | - | mA |
| V _O | output voltage | Active mode | [1][2][3] -0.5 | $V_{CCO} + 0.5$ | V |
| | | Suspend or 3-state mode | <u>[1]</u> –0.5 | +6.5 | V |
| I _O | output current | $V_O = 0 V \text{ to } V_{CCO}$ | [2] - | ±50 | mA |
| I _{CC} | supply current | $I_{CC(A)}$ or $I_{CC(B)}$; per V_{CC} pin | - | 100 | mA |

74LVC_LVCH8T245

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^[2] The An inputs/outputs, DIR and $\overline{\text{OE}}$ input circuit is referenced to $V_{\text{CC(A)}}$; The Bn inputs/outputs circuit is referenced to $V_{\text{CC(B)}}$.

^[3] If at least one of $V_{CC(A)}$ or $V_{CC(B)}$ is at GND level, the device goes into suspend mode.

Table 4. Limiting values ...continued

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|------------------|-------------------------|--|--------------|------|------|
| I_{GND} | ground current | per GND pin | -100 | - | mA |
| T _{stg} | storage temperature | | -65 | +150 | °C |
| P _{tot} | total power dissipation | $T_{amb} = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}$ | <u>[4]</u> _ | 500 | mW |

- [1] The minimum input voltage ratings and output voltage ratings may be exceeded if the input and output current ratings are observed.
- [2] V_{CCO} is the supply voltage associated with the output port.
- [3] $V_{CCO} + 0.5 \text{ V}$ should not exceed 6.5 V.
- [4] For TSSOP24 package: P_{tot} derates linearly at 5.5 mW/K above 60 °C. For DHVQFN24 package: P_{tot} derates linearly at 4.5 mW/K above 60 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

| Symbol | Parameter | Conditions | Min | Max | Unit |
|--------------------|-------------------------------------|--|--------------|-----------|------|
| $V_{CC(A)}$ | supply voltage A | | 1.2 | 5.5 | V |
| V _{CC(B)} | supply voltage B | | 1.2 | 5.5 | V |
| VI | input voltage | | 0 | 5.5 | V |
| Vo | output voltage | Active mode | <u>[1]</u> 0 | V_{CCO} | V |
| | | Suspend or 3-state mode | 0 | 5.5 | V |
| T _{amb} | ambient temperature | | -40 | +125 | °C |
| Δt/ΔV | input transition rise and fall rate | V _{CCI} = 1.2 V | [2] _ | 20 | ns/V |
| | | $V_{CCI} = 1.4 \text{ V to } 1.95 \text{ V}$ | - | 20 | ns/V |
| | | $V_{CCI} = 2.3 \text{ V to } 2.7 \text{ V}$ | - | 20 | ns/V |
| | | $V_{CCI} = 3 \text{ V to } 3.6 \text{ V}$ | - | 10 | ns/V |
| | | $V_{CCI} = 4.5 \text{ V to } 5.5 \text{ V}$ | - | 5 | ns/V |

^[1] V_{CCO} is the supply voltage associated with the output port.

9. Static characteristics

Table 6. Typical static characteristics at T_{amb} = 25 °C

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|------------------|---------------------------|---|--------------|------|-----|------|
| V_{OH} | HIGH-level output voltage | $V_I = V_{IH}$ or V_{IL} | <u>[1]</u> | | | |
| | | $I_{O} = -3 \text{ mA}; V_{CCO} = 1.2 \text{ V}$ | - | 1.09 | - | V |
| V _{OL} | LOW-level output voltage | $V_I = V_{IH}$ or V_{IL} | | | | |
| | | $I_O = 3 \text{ mA}; V_{CCO} = 1.2 \text{ V}$ | <u>[1]</u> - | 71 | V | |
| l _l | input leakage current | DIR, \overline{OE} input; $V_I = 0 \text{ V to } 5.5 \text{ V}$; $V_{CCI} = 1.2 \text{ V to } 5.5 \text{ V}$ | [2] _ | - | ±1 | μΑ |
| I _{BHL} | bus hold LOW current | A or B port; $V_I = 0.42 \text{ V}$; $V_{CCI} = 1.2 \text{ V}$ | [2] _ | 19 | - | μΑ |
| I _{BHH} | bus hold HIGH current | A or B port; $V_I = 0.78 \text{ V}$; $V_{CCI} = 1.2 \text{ V}$ | [2] _ | -19 | - | μΑ |

^[2] V_{CCI} is the supply voltage associated with the input port.

Table 6. Typical static characteristics at T_{amb} = 25 °C ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | | Min | Тур | Max | Unit |
|-------------------|---------------------------------|--|------------|-----|-----|-----|------|
| I _{BHLO} | bus hold LOW overdrive current | A or B port; $V_{CCI} = 1.2 \text{ V}$ | [2][3] | - | 19 | - | μΑ |
| I _{BHHO} | bus hold HIGH overdrive current | A or B port; $V_{CCI} = 1.2 \text{ V}$ | [2][3] | - | -19 | - | μΑ |
| l _{OZ} | OFF-state output current | A or B port; $V_O = 0 \text{ V or } V_{CCO}$; $V_{CCO} = 1.2 \text{ V to } 5.5 \text{ V}$ | [1] | - | - | ±1 | μΑ |
| | | suspend mode A port; $V_O = 0 \text{ V or } V_{CCO}$; $V_{CC(A)} = 5.5 \text{ V}$; $V_{CC(B)} = 0 \text{ V}$ | [1] | - | - | | μΑ |
| | | suspend mode B port; $V_O = 0 \text{ V or } V_{CCO}$; $V_{CC(A)} = 0 \text{ V}$; $V_{CC(B)} = 5.5 \text{ V}$ | <u>[1]</u> | - | - | | μΑ |
| I _{OFF} | power-off leakage current | A port; V_1 or $V_O = 0$ V to 5.5 V; $V_{CC(A)} = 0$ V; $V_{CC(B)} = 1.2$ V to 5.5 V | | - | - | ±1 | μΑ |
| | | B port; V_1 or $V_0 = 0$ V to 5.5 V; $V_{CC(B)} = 0$ V; $V_{CC(A)} = 1.2$ V to 5.5 V | | - | - | ±1 | μΑ |
| Cı | input capacitance | DIR, \overline{OE} input; $V_I = 0 \text{ V or } 3.3 \text{ V}; V_{CC(A)} = 3.3 \text{ V}$ | | - | 3 | - | pF |
| C _{I/O} | input/output capacitance | A and B port; $V_O = 3.3 \text{ V or } 0 \text{ V};$ $V_{CC(A)} = V_{CC(B)} = 3.3 \text{ V}$ | | - | 6.5 | - | pF |

^[1] V_{CCO} is the supply voltage associated with the output port.

Table 7. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | –40 °C to | +85 °C | –40 °C to +125 °C | | Unit |
|---------------|------------------------------------|---|------------------------|----------------------|------------------------|-----|------|
| | | | Min | Max | Min | Max | |
| V_{IH} | HIGH-level | data input | [1] | | | | |
| input voltage | V _{CCI} = 1.2 V | 0.8V _{CCI} | - | 0.8V _{CCI} | - | V | |
| | V _{CCI} = 1.4 V to 1.95 V | 0.65V _{CCI} | - | 0.65V _{CCI} | - | V | |
| | | $V_{CCI} = 2.3 \text{ V to } 2.7 \text{ V}$ | 1.7 | - | 1.7 | - | V |
| | | V _{CCI} = 3.0 V to 3.6 V | 2.0 | - | 2.0 | - | V |
| | | V _{CCI} = 4.5 V to 5.5 V | 0.7V _{CCI} | - | 0.7V _{CCI} | - | V |
| | | DIR, OE input | | | | | |
| | | V _{CCI} = 1.2 V | 0.8V _{CC(A)} | - | 0.8V _{CC(A)} | - | V |
| | | V _{CCI} = 1.4 V to 1.95 V | 0.65V _{CC(A)} | - | 0.65V _{CC(A)} | - | V |
| | | $V_{CCI} = 2.3 \text{ V to } 2.7 \text{ V}$ | 1.7 | - | 1.7 | - | V |
| | | V _{CCI} = 3.0 V to 3.6 V | 2.0 | - | 2.0 | - | V |
| | V _{CCI} = 4.5 V to 5.5 V | 0.7V _{CC(A)} | - | $0.7V_{CC(A)}$ | - | V | |

^[2] V_{CCI} is the supply voltage associated with the data input port.

^[3] To guarantee the node switches, an external driver must source/sink at least I_{BHLO} / I_{BHHO} when the input is in the range V_{IL} to V_{IH} .

Table 7. Static characteristics ...continued
At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | | -40 °C to | o +85 °C | -40 °C to | +125 °C | Unit |
|-----------------|--------------------------|---|------------|------------------------|------------------------|------------------------|------------------------|------|
| | | | | Min | Max | Min | Max | |
| V_{IL} | LOW-level | data input | <u>[1]</u> | | | ' | | |
| | input voltage | V _{CCI} = 1.2 V | | - | 0.2V _{CCI} | - | 0.2V _{CCI} | V |
| | | V _{CCI} = 1.4 V to 1.95 V | | - | $0.35V_{CCI}$ | - | 0.35V _{CCI} | V |
| | | V_{CCI} = 2.3 V to 2.7 V | | - | 0.7 | - | 0.7 | V |
| | | V _{CCI} = 3.0 V to 3.6 V | | - | 0.8 | - | 0.8 | V |
| | | V _{CCI} = 4.5 V to 5.5 V | | - | 0.3V _{CCI} | - | 0.3V _{CCI} | V |
| | | DIR, OE input | | | | | | |
| | | V _{CCI} = 1.2 V | | - | 0.2V _{CC(A)} | - | 0.2V _{CC(A)} | V |
| | | V _{CCI} = 1.4 V to 1.95 V | | - | 0.35V _{CC(A)} | - | 0.35V _{CC(A)} | V |
| | | V _{CCI} = 2.3 V to 2.7 V | | - | 0.7 | - | 0.7 | V |
| | | V _{CCI} = 3.0 V to 3.6 V | | - | 0.8 | - | 0.8 | V |
| | | V _{CCI} = 4.5 V to 5.5 V | | - | 0.3V _{CC(A)} | - | 0.3V _{CC(A)} | V |
| V _{OH} | HIGH-level | $V_I = V_{IH}$ | | | | | | |
| (| output voltage | $I_O = -100 \mu A;$ $V_{CCO} = 1.2 \text{ V to } 4.5 \text{ V}$ | [2] | V _{CCO} - 0.1 | - | V _{CCO} - 0.1 | - | V |
| | | $I_{O} = -6 \text{ mA}; V_{CCO} = 1.4 \text{ V}$ | | 1.0 | - | 1.0 | - | V |
| | | $I_{O} = -8 \text{ mA}; V_{CCO} = 1.65 \text{ V}$ | | 1.2 | - | 1.2 | - | V |
| | | $I_{O} = -12 \text{ mA}; V_{CCO} = 2.3 \text{ V}$ | | 1.9 | - | 1.9 | - | V |
| | | $I_{O} = -24 \text{ mA}; V_{CCO} = 3.0 \text{ V}$ | | 2.4 | - | 2.4 | - | V |
| | | $I_{O} = -32 \text{ mA}; V_{CCO} = 4.5 \text{ V}$ | | 3.8 | - | 3.8 | - | V |
| V _{OL} | LOW-level | $V_I = V_{IL}$ | [2] | | | | | |
| | output voltage | $I_O = 100 \mu A;$ $V_{CCO} = 1.2 \text{ V to } 4.5 \text{ V}$ | | - | 0.1 | - | 0.1 | V |
| | | $I_O = 6 \text{ mA}; V_{CCO} = 1.4 \text{ V}$ | | - | 0.3 | - | 0.3 | V |
| | | $I_O = 8 \text{ mA}; V_{CCO} = 1.65 \text{ V}$ | | - | 0.45 | - | 0.45 | V |
| | | $I_O = 12 \text{ mA}; V_{CCO} = 2.3 \text{ V}$ | | - | 0.3 | - | 0.3 | V |
| | | $I_O = 24 \text{ mA}; V_{CCO} = 3.0 \text{ V}$ | | - | 0.55 | - | 0.55 | V |
| | | $I_{O} = 32 \text{ mA}; V_{CCO} = 4.5 \text{ V}$ | | - | 0.55 | - | 0.55 | V |
| l | input leakage current | DIR, \overline{OE} input; $V_1 = 0 \text{ V to } 5.5 \text{ V}$; $V_{CCI} = 1.2 \text{ V to } 5.5 \text{ V}$ | | - | ±2 | - | ±10 | μΑ |
| BHL | bus hold LOW | A or B port | <u>[1]</u> | | | | | |
| | current | V _I = 0.49 V; V _{CCI} = 1.4 V | | 15 | - | 10 | - | μΑ |
| | | $V_{I} = 0.58 \text{ V}; V_{CCI} = 1.65 \text{ V}$ | | 25 | - | 20 | - | μΑ |
| | | $V_{I} = 0.70 \text{ V}; V_{CCI} = 2.3 \text{ V}$ | | 45 | - | 45 | - | μΑ |
| | | $V_{I} = 0.80 \text{ V}; V_{CCI} = 3.0 \text{ V}$ | | 100 | - | 80 | - | μΑ |
| | | V _I = 1.35 V; V _{CCI} = 4.5 V | | 100 | - | 100 | - | μА |

 Table 7.
 Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | | –40 °C to +85 °C | | -40 °C to | +125 °C | Unit |
|-------------------|---------------------------------------|--|------------|------------------|-----|-----------|---------|------|
| | | | Min | Max | Min | Max | | |
| I _{BHH} | bus hold HIGH | A or B port | <u>[1]</u> | | | | | |
| | current | V _I = 0.91 V; V _{CCI} = 1.4 V | | -15 | - | -10 | - | μΑ |
| | | V _I = 1.07 V; V _{CCI} = 1.65 V | | -25 | - | -20 | - | μΑ |
| | | V _I = 1.70 V; V _{CCI} = 2.3 V | | -45 | - | -45 | - | μΑ |
| | | V _I = 2.00 V; V _{CCI} = 3.0 V | | -100 | - | -80 | - | μΑ |
| | | V _I = 3.15 V; V _{CCI} = 4.5 V | | -100 | - | -100 | - | μΑ |
| I _{BHLO} | bus hold LOW | A or B port | [1][3] | | | | | |
| | overdrive | V _{CCI} = 1.6 V | | 125 | - | 125 | - | μΑ |
| | current | V _{CCI} = 1.95 V | | 200 | - | 200 | - | μΑ |
| | | V _{CCI} = 2.7 V | | 300 | - | 300 | - | μΑ |
| | | V _{CCI} = 3.6 V | | 500 | - | 500 | - | μΑ |
| | | V _{CCI} = 5.5 V | | 900 | - | 900 | - | μΑ |
| | bus hold HIGH overdrive current | A or B port | [1][3] | | | | | |
| | | V _{CCI} = 1.6 V | | -125 | - | -125 | - | μΑ |
| | | V _{CCI} = 1.95 V | | -200 | - | -200 | - | μΑ |
| | | V _{CCI} = 2.7 V | | -300 | - | -300 | - | μΑ |
| | | V _{CCI} = 3.6 V | | -500 | - | -500 | - | μΑ |
| | | V _{CCI} = 5.5 V | | -900 | - | -900 | - | μΑ |
| l _{OZ} | OFF-state output current | A or B port; $V_O = 0 \text{ V or } V_{CCO}$; $V_{CCO} = 1.2 \text{ V to } 5.5 \text{ V}$ | [2] | - | ±2 | - | ±10 | μА |
| | | suspend mode A port; $V_O = 0 \text{ V or } V_{CCO}; V_{CC(A)} = 5.5 \text{ V};$ $V_{CC(B)} = 0 \text{ V}$ | [2] | - | ±2 | - | ±10 | μА |
| | | suspend mode B port; $V_O = 0 \text{ V or } V_{CCO}; V_{CC(A)} = 0 \text{ V};$ $V_{CC(B)} = 5.5 \text{ V}$ | [2] | - | ±2 | - | ±10 | μА |
| I _{OFF} | power-off leakage current | A port; V_1 or $V_0 = 0$ V to 5.5 V; $V_{CC(A)} = 0$ V; $V_{CC(B)} = 1.2$ V to 5.5 V | | - | ±2 | - | ±10 | μА |
| | Cullent | B port; V_I or $V_O = 0$ V to 5.5 V; $V_{CC(B)} = 0$ V; $V_{CC(A)} = 1.2$ V to 5.5 V | | - | ±2 | - | ±10 | μА |

 Table 7.
 Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | | -40 °C t | o +85 °C | -40 °C to +125 °C | | Unit |
|-----------------|---------------------------|--|-----|----------|----------|-------------------|-----|------|
| | | | Ī | Min | Max | Min | Max | |
| I _{CC} | supply current | A port; $V_I = 0 \text{ V or } V_{CCI}$; $I_O = 0 \text{ A}$ | [1] | | • | ' | | ' |
| | | $V_{CC(A)}$, $V_{CC(B)} = 1.2 \text{ V to } 5.5 \text{ V}$ | | - | 15 | - | 20 | μΑ |
| | | $V_{CC(A)} = 5.5 \text{ V}; V_{CC(B)} = 0 \text{ V}$ | | - | 15 | - | 20 | μΑ |
| | | $V_{CC(A)} = 0 \text{ V}; V_{CC(B)} = 5.5 \text{ V}$ | | -2 | - | -4 | - | μΑ |
| | | B port; $V_I = 0 V \text{ or } V_{CCI}$; $I_O = 0 A$ | | | | | | |
| | | $V_{CC(A)}$, $V_{CC(B)} = 1.2 \text{ V to } 5.5 \text{ V}$ | | - | 15 | - | 20 | μΑ |
| | | $V_{CC(B)} = 0 \text{ V}; V_{CC(A)} = 5.5 \text{ V}$ | | -2 | - | -4 | - | μΑ |
| | | $V_{CC(B)} = 5.5 \text{ V}; V_{CC(A)} = 0 \text{ V}$ | | - | 15 | - | 20 | μΑ |
| | | A plus B port ($I_{CC(A)} + I_{CC(B)}$); $I_O = 0$ A; $V_I = 0$ V or V_{CCI} | | | | | | |
| | | $V_{CC(A)}$, $V_{CC(B)} = 1.2 \text{ V to } 5.5 \text{ V}$ | | - | 25 | - | 30 | μΑ |
| ΔI_{CC} | additional supply current | per input; $V_{CC(A)}$, $V_{CC(B)} = 3.0 \text{ V to } 5.5 \text{ V}$ | | | | | | |
| | | DIR and \overline{OE} input; DIR or \overline{OE} input at $V_{CC(A)} - 0.6 \text{ V}$; A port at $V_{CC(A)}$ or GND; B port = open | | - | 50 | - | 75 | μА |
| | | A port; A port at $V_{CC(A)} - 0.6 \text{ V}$; DIR at $V_{CC(A)}$; B port = open | [4] | - | 50 | - | 75 | μА |
| | | B port; B port at $V_{CC(B)} - 0.6 \text{ V}$; DIR at GND; A port = open | [4] | - | 50 | - | 75 | μΑ |

^[1] V_{CCI} is the supply voltage associated with the data input port.

^[2] V_{CCO} is the supply voltage associated with the output port.

^[3] To guarantee the node switches, an external driver must source/sink at least I_{BHLO} / I_{BHHO} when the input is in the range V_{IL} to V_{IH}.

^[4] For non bus hold parts only (74LVC8T245).

10. Dynamic characteristics

Table 8. Typical dynamic characteristics at $V_{CC(A)} = 1.2 \text{ V}$ and $T_{amb} = 25 \, ^{\circ}\text{C}_{-}^{11}$

Voltages are referenced to GND (ground = 0 V); for test circuit see Figure 7; for waveforms see Figure 5 and Figure 6.

| Symbol | Parameter | Conditions | V _{CC(B)} | | | | | | | |
|------------------|-------------------|------------|--------------------|-------|-------|-------|-------|-------|----|--|
| | | | 1.2 V | 1.5 V | 1.8 V | 2.5 V | 3.3 V | 5.0 V | | |
| t _{pd} | propagation delay | An to Bn | 11.0 | 8.5 | 7.4 | 6.2 | 5.7 | 5.4 | ns | |
| | | Bn to An | 11.0 | 10.0 | 9.5 | 9.1 | 8.9 | 8.9 | ns | |
| t _{dis} | disable time | OE to An | 9.5 | 9.5 | 9.5 | 9.5 | 9.5 | 9.5 | ns | |
| | | OE to Bn | 10.2 | 8.2 | 7.8 | 6.7 | 7.3 | 6.4 | ns | |
| t _{en} | enable time | OE to An | 13.5 | 13.5 | 13.5 | 13.5 | 13.5 | 13.5 | ns | |
| | | OE to Bn | 13.6 | 10.3 | 8.9 | 7.5 | 7.1 | 7.0 | ns | |

^[1] t_{pd} is the same as t_{PLH} and t_{PHL}; t_{dis} is the same as t_{PLZ} and t_{PHZ}; t_{en} is the same as t_{PZL} and t_{PZH}.

Table 9. Typical dynamic characteristics at $V_{CC(B)} = 1.2 \text{ V}$ and $T_{amb} = 25 \,^{\circ}\text{C}\frac{[1]}{2}$

Voltages are referenced to GND (ground = 0 V); for test circuit see Figure 7; for waveforms see Figure 5 and Figure 6.

| Symbol | ymbol Parameter Conditions | | | V _{CC(A)} | | | | | | | |
|------------------|----------------------------|----------|-------|--------------------|-------|-------|-------|-------|----|--|--|
| | | | 1.2 V | 1.5 V | 1.8 V | 2.5 V | 3.3 V | 5.0 V | | | |
| t_{pd} | propagation delay | An to Bn | 11.0 | 10.0 | 9.5 | 9.1 | 8.9 | 8.8 | ns | | |
| | | Bn to An | 11.0 | 8.5 | 7.3 | 6.2 | 5.7 | 5.4 | ns | | |
| t _{dis} | disable time | OE to An | 9.5 | 6.8 | 5.4 | 3.8 | 4.1 | 3.1 | ns | | |
| | | OE to Bn | 10.2 | 9.1 | 8.6 | 8.1 | 7.8 | 7.8 | ns | | |
| t _{en} | enable time | OE to An | 13.5 | 9.0 | 6.9 | 4.8 | 3.8 | 3.2 | ns | | |
| | | OE to Bn | 13.6 | 12.5 | 12.0 | 11.5 | 11.4 | 11.4 | ns | | |

^[1] t_{pd} is the same as t_{PLH} and t_{PHL} ; t_{dis} is the same as t_{PLZ} and t_{PHZ} ; t_{en} is the same as t_{PZL} and t_{PZH} .

Table 10. Typical power dissipation capacitance at $V_{CC(A)} = V_{CC(B)}$ and $T_{amb} = 25 \, {}^{\circ}C_{C[1][2]}$ Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | V _{CC(A)} and V _{CC(B)} | | | | | | |
|----------|-------------------------------|---|---|-------|-------|-------|----|--|--|
| | | | 1.8 V | 2.5 V | 3.3 V | 5.0 V | | | |
| C_{PD} | power dissipation capacitance | A port: (direction A to B); B port: (direction B to A) | 1 | 1 | 1 | 2 | pF | | |
| | | A port: (direction B to A); B port: (direction A to B) | 13 | 13 | 13 | 13 | pF | | |

[1] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma (C_L \times V_{CC}^2 \times f_o)$ where:

f_i = input frequency in MHz;

 f_0 = output frequency in MHz;

C_L = load capacitance in pF;

 V_{CC} = supply voltage in V;

N = number of inputs switching;

 $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

[2] $f_i = 10 \text{ MHz}; \ V_I = \text{GND to } V_{CC}; \ t_r = t_f = 1 \text{ ns}; \ C_L = 0 \text{ pF}; \ R_L = \infty \ \Omega.$

Table 11. Dynamic characteristics for temperature range -40 °C to +85 °C[1]

Voltages are referenced to GND (ground = 0 V); for test circuit see Figure 7; for wave forms see Figure 5 and Figure 6.

| | | 1 E V | | 1 | | V _C | | | | | | |
|----------------|--|--|--|---|----------|--|----------|--|----------|----------|--|---|
| | | 1.5 V | ± 0.1 V | 1.8 V ± | 0.15 V | 2.5 V | ± 0.2 V | 3.3 V | ± 0.3 V | 5.0 V | ± 0.5 V | |
| | | Min | Max | Min | Max | Min | Max | Min | Max | Min | Max | |
| ± 0.1 V | | | | | | | | | | I | | |
| agation | An to Bn | 1.7 | 27 | 1.7 | 23 | 1.3 | 18 | 1.0 | 15 | 8.0 | 13 | ns |
| 1 | Bn to An | 0.9 | 27 | 0.9 | 25 | 8.0 | 23 | 0.7 | 23 | 0.7 | 22 | ns |
| le time | OE to An | 1.5 | 30 | 1.5 | 30 | 1.5 | 30 | 1.5 | 30 | 1.4 | 30 | ns |
| | OE to Bn | 2.4 | 34 | 2.4 | 33 | 1.9 | 15 | 1.7 | 14 | 1.3 | 12 | ns |
| le time | OE to An | 0.4 | 34 | 0.4 | 34 | 0.4 | 34 | 0.4 | 34 | 0.4 | 34 | ns |
| | OE to Bn | 1.8 | 36 | 1.8 | 34 | 1.5 | 18 | 1.2 | 15 | 0.9 | 13 | ns |
| ± 0.15 V | | | | | | | | | | | | |
| agation | An to Bn | 1.7 | 25 | 1.7 | 21.9 | 1.3 | 9.2 | 1.0 | 7.4 | 0.8 | 7.1 | ns |
| 1 | Bn to An | 0.9 | 23 | 0.9 | 23.8 | 0.8 | 23.6 | 0.7 | 23.4 | 0.7 | 23.4 | ns |
| le time | OE to An | 1.5 | 30 | 1.5 | 29.6 | 1.5 | 29.4 | 1.5 | 29.3 | 1.4 | 29.2 | ns |
| | OE to Bn | 2.4 | 33 | 2.4 | 32.2 | 1.9 | 13.1 | 1.7 | 12.0 | 1.3 | 10.3 | ns |
| le time | OE to An | 0.4 | 24 | 0.4 | 24.0 | 0.4 | 23.8 | 0.4 | 23.7 | 0.4 | 23.7 | ns |
| | OE to Bn | 1.8 | 34 | 1.8 | 32.0 | 1.5 | 16.0 | 1.2 | 12.6 | 0.9 | 10.8 | ns |
| ± 0.2 V | | | | | | | | | | | | |
| agation | An to Bn | 1.5 | 23 | 1.5 | 21.4 | 1.2 | 9.0 | 8.0 | 6.2 | 0.6 | 4.8 | ns |
| ′ | Bn to An | 1.2 | 18 | 1.2 | 9.3 | 1.0 | 9.1 | 1.0 | 8.9 | 0.9 | 8.8 | ns |
| le time | OE to An | 1.4 | 9.0 | 1.4 | 9.0 | 1.4 | 9.0 | 1.4 | 9.0 | 1.4 | 9.0 | ns |
| | OE to Bn | 2.3 | 31 | 2.3 | 29.6 | 1.8 | 11.0 | 1.7 | 9.3 | 0.9 | 6.9 | ns |
| le time | OE to An | 1.0 | 10.9 | 1.0 | 10.9 | 1.0 | 10.9 | 1.0 | 10.9 | 1.0 | 10.9 | ns |
| | OE to Bn | 1.7 | 32 | 1.7 | 28.2 | 1.5 | 12.9 | 1.2 | 9.4 | 1.0 | 6.9 | ns |
| ± 0.3 V | | | | | | | | | | | | |
| agation | An to Bn | 1.5 | 23 | 1.5 | 21.2 | 1.1 | 8.8 | 8.0 | 6.3 | 0.5 | 4.4 | ns |
| 1 | Bn to An | 8.0 | 15 | 8.0 | 7.2 | 8.0 | 6.2 | 0.7 | 6.1 | 0.6 | 6.0 | ns |
| le time | OE to An | 1.6 | 8.2 | 1.6 | 8.2 | 1.6 | 8.2 | 1.6 | 8.2 | 1.6 | 8.2 | ns |
| | OE to Bn | 2.1 | 30 | 2.1 | 29.0 | 1.7 | 10.3 | 1.5 | 8.6 | 8.0 | 6.3 | ns |
| le time | OE to An | 0.8 | 8.1 | 0.8 | 8.1 | 8.0 | 8.1 | 0.8 | 8.1 | 8.0 | 8.1 | ns |
| | OE to Bn | 1.8 | 31 | 1.8 | 27.7 | 1.4 | 12.4 | 1.1 | 8.5 | 0.9 | 6.4 | ns |
| ± 0.5 V | | | | | | | | | | | | |
| agation | An to Bn | 1.5 | 22 | 1.5 | 21.4 | 1.0 | 8.8 | 0.7 | 6.0 | 0.4 | 4.2 | ns |
| <u>'</u> | Bn to An | 0.7 | 13 | 0.7 | 7.0 | 0.4 | 4.8 | 0.3 | 4.5 | 0.3 | 4.3 | ns |
| le time | OE to An | 0.3 | 5.4 | 0.3 | 5.4 | 0.3 | 5.4 | 0.3 | 5.4 | 0.3 | 5.4 | ns |
| | OE to Bn | 2.0 | 30 | 2.0 | 28.7 | 1.6 | 9.7 | 1.4 | 8.0 | 0.7 | 5.7 | ns |
| le time | OE to An | 0.7 | 6.4 | 0.7 | 6.4 | 0.7 | 6.4 | 0.7 | 6.4 | 0.7 | 6.4 | ns |
| | OE to Bn | 1.5 | 31 | 1.5 | 27.6 | 1.3 | 11.4 | 1.0 | 8.1 | 0.9 | 6.0 | ns |
| | agation viole time de time | An to Bn Bn to An OE to An OE to Bn le time OE to An OE to Bn ### 0.15 V Agation An to Bn Bn to An OE to An OE to Bn ### 0.2 V Agation An to Bn Bn to An OE to Bn #### 0.2 V Agation An to Bn Bn to An OE to Bn #### 0.2 V Agation An to Bn Bn to An OE to Bn ##### 0.5 V Agation An to Bn DE to An OE to Bn ################################### | An to Bn 1.7 Bn to An 0.9 De to An 1.5 DE to Bn 2.4 DE to Bn 1.8 DE to Bn 1.8 DE to Bn 1.7 An to Bn 1.7 Bn to An 0.9 DE to Bn 1.8 DE to Bn 1.8 DE to Bn 1.7 DE to Bn 1.5 DE to Bn 1.5 DE to Bn 1.5 DE to Bn 1.5 DE to Bn 1.8 DE to Bn 1.5 DE to Bn 1.5 DE to Bn 1.6 DE to Bn 1.6 DE to Bn 1.7 DE to Bn 1.8 DE to Bn 1.8 DE to Bn 1.8 DE to Bn 1.8 DE to Bn 1.7 DE to Bn 1.8 DE to Bn 1.8 | An to Bn Description An to Bn 1.7 27 | An to Bn | And to Bn 1.7 27 1.7 23 Bn to An 0.9 27 0.9 25 OE to An 1.5 30 1.5 30 DE to Bn 2.4 34 2.4 33 Ide time OE to An 0.4 34 0.4 34 DE to Bn 1.8 36 1.8 34 ± 0.15 V Bn to An 0.9 23 0.9 23.8 Determine OE to An 1.5 30 1.5 29.6 DE to Bn 2.4 33 2.4 32.2 Determine OE to An 0.4 24 0.4 24.0 DE to Bn 1.8 34 1.8 32.0 ± 0.2 V Bn to An 1.2 18 1.2 9.3 Determine OE to An 1.4 9.0 1.4 9.0 Determine OE to An 1.0 10.9 1.0 10.9 Determine OE to An | An to Bn | And to Bn 1.7 27 1.7 23 1.3 18 Bn to An 0.9 27 0.9 25 0.8 23 Ole time OE to An 1.5 30 1.5 30 1.5 30 OE to Bn 2.4 34 2.4 33 1.9 15 Ide time OE to An 0.4 34 0.4 34 0.4 34 Jet time OE to An 0.4 34 0.4 34 0.4 34 Jet time OE to Bn 1.8 36 1.8 34 1.5 18 Jet time OE to An 0.9 23 0.9 23.8 0.8 23.6 Jet time OE to An 1.5 30 1.5 29.6 1.5 29.4 Jet time OE to An 0.4 24 0.4 24.0 0.4 23.8 Jet time OE to An 1.5 23 1.5 21.5 21.9 | An to Bn | An to Bn | An to Bn 1.7 27 1.7 23 1.3 18 1.0 15 0.8 Bn to An 0.9 27 0.9 25 0.8 23 0.7 23 0.7 OE to An 1.5 30 1.5 30 1.5 30 1.5 30 1.4 OE to Bn 2.4 34 2.4 33 1.9 15 1.7 14 1.3 Ie time OE to An 0.4 34 0.4 34 0.4 34 0.4 34 0.4 34 0.4 34 0.4 34 0.4 34 0.4 34 0.4 34 0.4 34 0.4 34 0.4 34 0.4 34 0.4 34 0.4 34 0.4 34 0.4 34 0.4 34 0.4 22.9 1.5 29.4 1.5 29.3 1.4 de time OE to An 0.4 24 0.4 | An to Bn 1.7 27 1.7 23 1.3 18 1.0 15 0.8 13 An to Bn to An 0.9 27 0.9 25 0.8 23 0.7 23 0.7 22 Be time OE to An 1.5 30 1.5 30 1.5 30 1.5 30 1.4 30 Be time OE to An 0.4 34 0.8 7.1 0.8 7.1 0.8 7.1 0.8 3.1 <t< td=""></t<> |

^[1] t_{pd} is the same as t_{PLH} and t_{PHL} ; t_{dis} is the same as t_{PLZ} and t_{PHZ} ; t_{en} is the same as t_{PZL} and t_{PZH} .

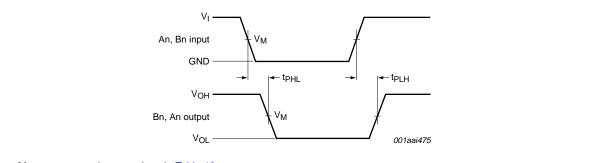
Table 12. Dynamic characteristics for temperature range -40 °C to +125 °C[1]

Voltages are referenced to GND (ground = 0 V); for test circuit see Figure 7; for wave forms see Figure 5 and Figure 6.

| 18 0.8 28 0.3 34 1.4 17 1.3 40 0.4 18 0.8 27.4 0.3 33.3 1.4 | Max 3 16 7 26 4 34 3 15 4 40 9 16 3 11.1 7 27.4 | ns ns ns ns ns |
|--|--|--|
| 18 0.8 28 0.7 34 1.4 17 1.3 40 0.4 18 0.9 11.4 0.8 27.4 0.7 33.3 1.4 | 3 16 7 26 4 34 3 15 4 40 9 16 3 11.1 7 27.4 | ns ns ns ns ns |
| 28 0.3 34 1.4 17 1.3 40 0.4 18 0.9 11.4 0.8 27.4 0.3 33.3 1.4 | 7 26 4 34 3 15 4 40 9 16 3 11.1 7 27.4 | ns ns ns ns ns |
| 28 0.3 34 1.4 17 1.3 40 0.4 18 0.9 11.4 0.8 27.4 0.3 33.3 1.4 | 7 26 4 34 3 15 4 40 9 16 3 11.1 7 27.4 | ns ns ns ns ns |
| 34 1.4 17 1.3 40 0.4 18 0.9 11.4 0.8 27.4 0.3 33.3 1.4 | 4 34 3 15 4 40 9 16 3 11.1 7 27.4 | ns ns ns ns |
| 17 1.3 40 0.4 18 0.9 11.4 0.8 27.4 0.3 33.3 1.4 | 3 15 4 40 9 16 3 11.1 7 27.4 | ns ns ns |
| 40 0.4 18 0.9 11.4 0.8 27.4 0.7 33.3 1.4 | 4 40 9 16 3 11.1 7 27.4 | ns ns |
| 18 0.9 11.4 0.8 27.4 0.7 33.3 1.4 | 9 16 3 11.1 7 27.4 | ns |
| 11.4 0.8 27.4 0.7 33.3 1.4 | 3 11.1 7 27.4 | ns |
| 27.4 0.7 33.3 1.4 | 7 27.4 | |
| 27.4 0.7 33.3 1.4 | 7 27.4 | |
| 33.3 1.4 | | |
| | 1 22.2 | ns |
| 160 11 | 4 33.2 | ns |
| . 0.0 | 3 14.3 | ns |
| 27.7 0.4 | 4 27.7 | ns |
| 16.6 0.9 | 9 14.8 | ns |
| | | |
| 10.2 0.6 | 8.8 | ns |
| 12.9 0.9 | 9 12.8 | ns |
| 13 1.4 | 4 13 | ns |
| 14.3 0.9 | 9 10.9 | ns |
| 17.2 1.0 | 17.3 | ns |
| 14.1 1.0 | 11.2 | ns |
| | | |
| 10.3 0.5 | 5 10.4 | ns |
| 10.1 0.6 | 6 10 | ns |
| 12.2 1.6 | 6 12.2 | ns |
| 12.6 0.8 | 3 10.3 | ns |
| 13.2 0.8 | 3 13.6 | ns |
| 12.9 0.9 | 9 10.9 | ns |
| | | |
| 10 0.4 | 4 8.2 | ns |
| 8.5 0.3 | 8.3 | ns |
| 9.4 0.3 | 3 9.4 | ns |
| 12 0.7 | 7 9.7 | ns |
| 10.9 0.7 | 7 10.9 | ns |
| 13.7 0.9 | 9 10.7 | ns |
| | 27.7 0.4 16.6 0.9 10.2 0.6 12.9 0.9 13 1.4 14.3 0.9 17.2 1.6 10.1 0.6 12.2 1.6 12.6 0.8 13.2 0.8 12.9 0.9 10 0.4 8.5 0.6 9.4 0.6 12 0.7 10.9 0.7 | 27.7 0.4 27.7 16.6 0.9 14.8 10.2 0.6 8.8 12.9 0.9 12.8 13 1.4 13 14.3 0.9 10.9 17.2 1.0 17.3 14.1 1.0 11.2 10.3 0.5 10.4 10.1 0.6 10 12.2 1.6 12.2 12.6 0.8 10.3 13.2 0.8 13.6 12.9 0.9 10.9 10 0.4 8.2 8.5 0.3 8.3 9.4 0.3 9.4 12 0.7 9.7 10.9 0.7 10.9 |

^[1] t_{pd} is the same as t_{PLH} and t_{PHL} ; t_{dis} is the same as t_{PLZ} and t_{PHZ} ; t_{en} is the same as t_{PZL} and t_{PZH} .

11. Waveforms



Measurement points are given in Table 13.

 V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 5. The data input (An, Bn) to output (Bn, An) propagation delay times

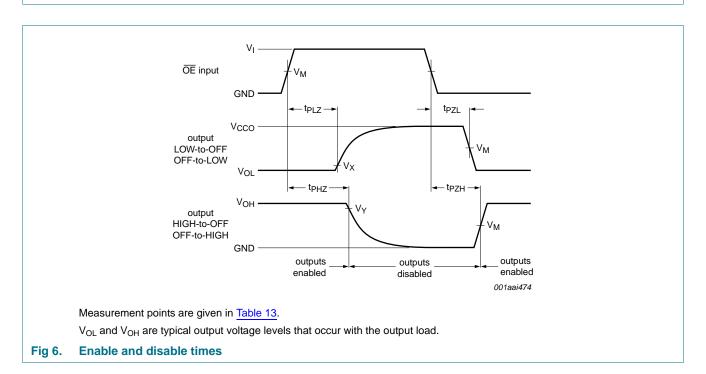
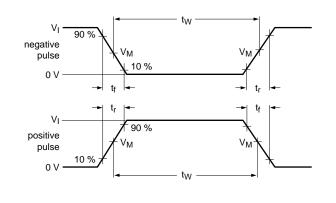


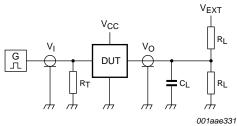
Table 13. Measurement points

| Supply voltage | Input[1] | Output[2] | Output ^[2] | | | | | | |
|---|---------------------|---------------------|--------------------------|--------------------------|--|--|--|--|--|
| V _{CC(A)} , V _{CC(B)} | V _M | V _M | V _X | V _Y | | | | | |
| 1.2 V to 1.6 V | 0.5V _{CCI} | 0.5V _{CCO} | V _{OL} + 0.1 V | V _{OH} – 0.1 V | | | | | |
| 1.65 V to 2.7 V | 0.5V _{CCI} | 0.5V _{CCO} | V _{OL} + 0.15 V | V _{OH} – 0.15 V | | | | | |
| 3.0 V to 5.5 V | 0.5V _{CCI} | 0.5V _{CCO} | V _{OL} + 0.3 V | $V_{OH} - 0.3 V$ | | | | | |

[1] V_{CCI} is the supply voltage associated with the data input port.

[2] V_{CCO} is the supply voltage associated with the output port.





Test data is given in Table 14.

R_L = Load resistance.

 C_L = Load capacitance including jig and probe capacitance.

 R_T = Termination resistance.

 V_{EXT} = External voltage for measuring switching times.

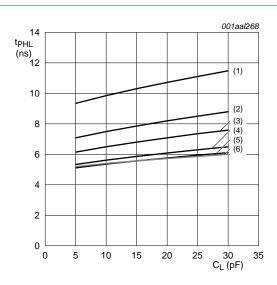
Fig 7. Load circuitry for switching times

Table 14. Test data

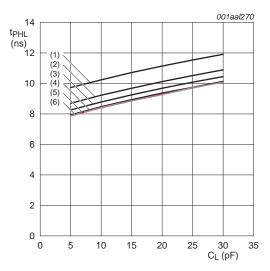
| Supply voltage | Input | | Load | | V _{EXT} | | | |
|---|--------------------|----------------------------|-------|----------------|-------------------------------------|-------------------------------------|---|--|
| V _{CC(A)} , V _{CC(B)} | V _I [1] | ∆ t/ ∆ V [2] | CL | R _L | t _{PLH} , t _{PHL} | t _{PZH} , t _{PHZ} | t _{PZL} , t _{PLZ} [3] | |
| 1.2 V to 5.5 V | V_{CCI} | ≤ 1.0 ns/V | 15 pF | 2 kΩ | open | GND | 2V _{CCO} | |

- [1] V_{CCI} is the supply voltage associated with the data input port.
- [2] dV/dt ≥ 1.0 V/ns.
- [3] V_{CCO} is the supply voltage associated with the output port.

12. Typical propagation delay characteristics

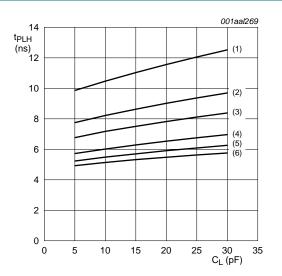


a. HIGH to LOW propagation delay (A to B)

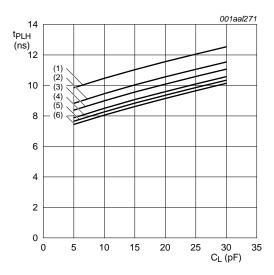


- c. HIGH to LOW propagation delay (B to A)
- (1) $V_{CC(B)} = 1.2 \text{ V}.$
- (2) $V_{CC(B)} = 1.5 \text{ V}.$
- (3) $V_{CC(B)} = 1.8 \text{ V}.$
- (4) $V_{CC(B)} = 2.5 \text{ V}.$
- (5) $V_{CC(B)} = 3.3 \text{ V}.$
- (6) $V_{CC(B)} = 5.0 \text{ V}.$

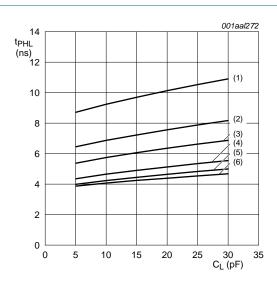


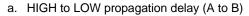


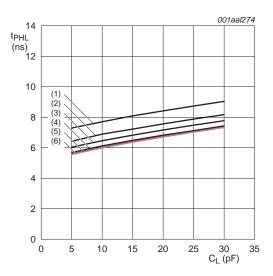
b. LOW to HIGH propagation delay (A to B)



d. LOW to HIGH propagation delay (B to A)



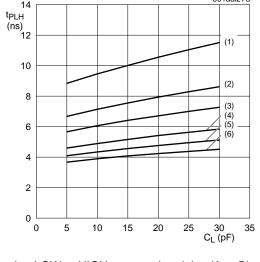




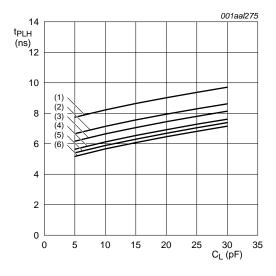
c. HIGH to LOW propagation delay (B to A)



- (2) $V_{CC(B)} = 1.5 \text{ V}.$
- (3) $V_{CC(B)} = 1.8 \text{ V}.$
- (4) $V_{CC(B)} = 2.5 \text{ V}.$
- (5) $V_{CC(B)} = 3.3 \text{ V}.$
- (6) $V_{CC(B)} = 5.0 \text{ V}.$

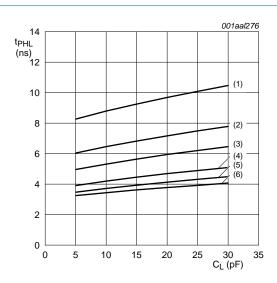


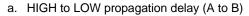
b. LOW to HIGH propagation delay (A to B)

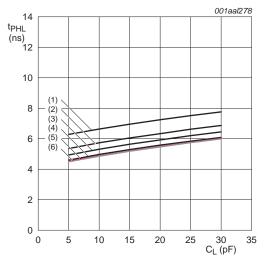


d. LOW to HIGH propagation delay (B to A)







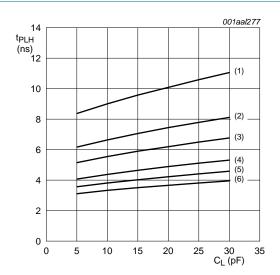


c. HIGH to LOW propagation delay (B to A)

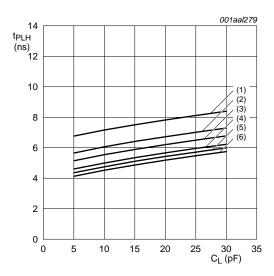


- (2) $V_{CC(B)} = 1.5 \text{ V}.$
- (3) $V_{CC(B)} = 1.8 \text{ V}.$
- (4) $V_{CC(B)} = 2.5 \text{ V}.$
- (5) $V_{CC(B)} = 3.3 \text{ V}.$
- (6) $V_{CC(B)} = 5.0 \text{ V}.$

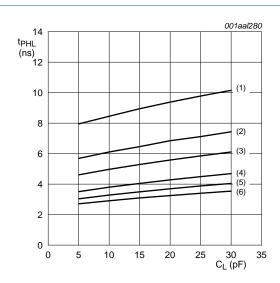
Fig 10. Typical propagation delay versus load capacitance; T_{amb} = 25 °C; V_{CC(A)} = 1.8 V

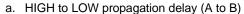


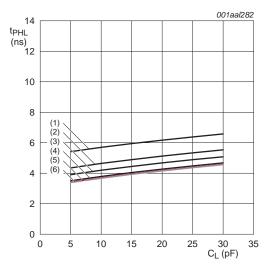
b. LOW to HIGH propagation delay (A to B)



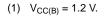
d. LOW to HIGH propagation delay (B to A)





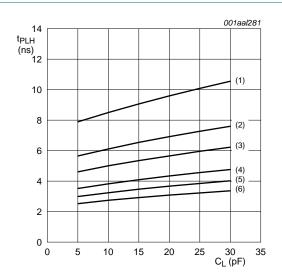


c. HIGH to LOW propagation delay (B to A)

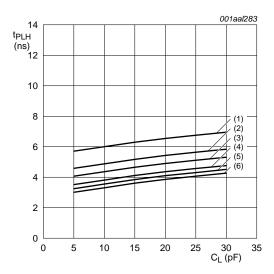


- (2) $V_{CC(B)} = 1.5 \text{ V}.$
- (3) $V_{CC(B)} = 1.8 \text{ V}.$
- (4) $V_{CC(B)} = 2.5 \text{ V}.$
- (5) $V_{CC(B)} = 3.3 \text{ V}.$
- (6) $V_{CC(B)} = 5.0 \text{ V}.$

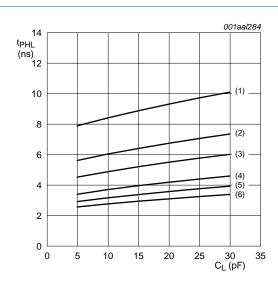


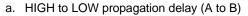


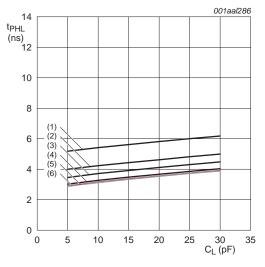
b. LOW to HIGH propagation delay (A to B)



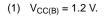
d. LOW to HIGH propagation delay (B to A)



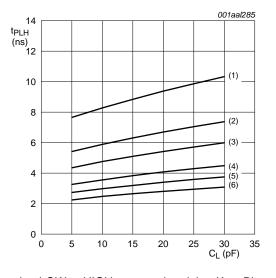




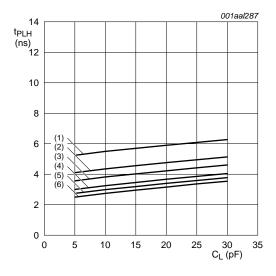
c. HIGH to LOW propagation delay (B to A)



- (2) $V_{CC(B)} = 1.5 \text{ V}.$
- (3) $V_{CC(B)} = 1.8 \text{ V}.$
- (4) $V_{CC(B)} = 2.5 \text{ V}.$
- (5) $V_{CC(B)} = 3.3 \text{ V}.$
- (6) $V_{CC(B)} = 5.0 \text{ V}.$

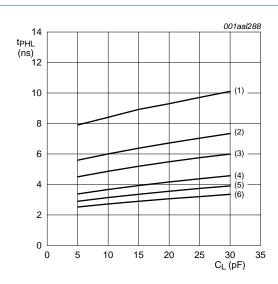


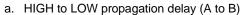
b. LOW to HIGH propagation delay (A to B)

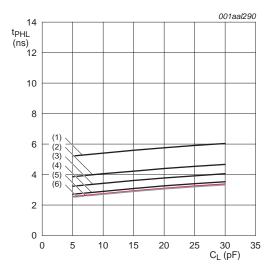


d. LOW to HIGH propagation delay (B to A)







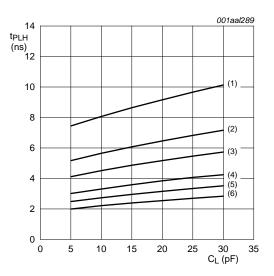


c. HIGH to LOW propagation delay (B to A)

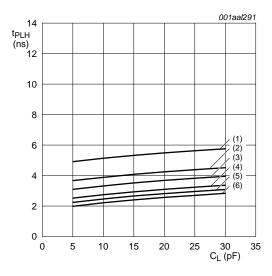


- (2) $V_{CC(B)} = 1.5 \text{ V}.$
- (3) $V_{CC(B)} = 1.8 \text{ V}.$
- (4) $V_{CC(B)} = 2.5 \text{ V}.$
- (5) $V_{CC(B)} = 3.3 \text{ V}.$
- (6) $V_{CC(B)} = 5.0 \text{ V}.$

Fig 13. Typical propagation delay versus load capacitance; T_{amb} = 25 °C; $V_{CC(A)}$ = 5 V



b. LOW to HIGH propagation delay (A to B)



d. LOW to HIGH propagation delay (B to A)

13. Application information

13.1 Unidirectional logic level-shifting application

The circuit given in <u>Figure 14</u> is an example of the 74LVC8T245; 74LVCH8T245 being used in an unidirectional logic level-shifting application.

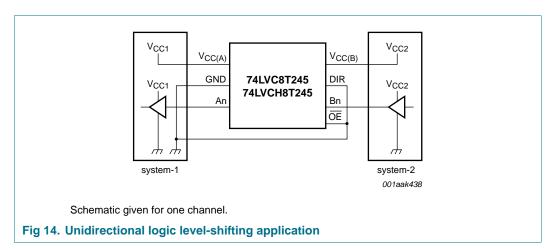
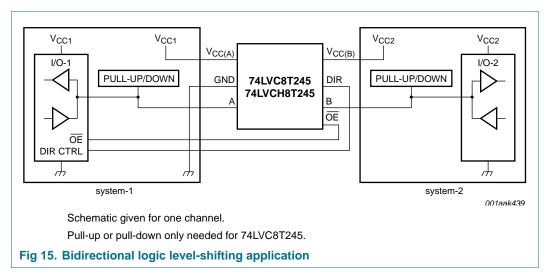


Table 15. Description unidirectional logic level-shifting application

| Name | Function | Description |
|--------------------|-----------|---|
| $V_{CC(A)}$ | V_{CC1} | supply voltage of system-1 (1.2 V to 5.5 V) |
| GND | GND | device GND |
| Α | OUT | output level depends on V _{CC1} voltage |
| В | IN | input threshold value depends on V _{CC2} voltage |
| DIR | DIR | the GND (LOW level) determines B port to A port direction |
| V _{CC(B)} | V_{CC2} | supply voltage of system-2 (1.2 V to 5.5 V) |
| ŌE | ŌĒ | The GND (LOW level) enables the output ports |
| | | |

13.2 Bidirectional logic level-shifting application

<u>Figure 15</u> shows the 74LVC8T245; 74LVCH8T245 being used in a bidirectional logic level-shifting application.



<u>Table 16</u> gives a sequence that will illustrate data transmission from system-1 to system-2 and then from system-2 to system-1.

Table 16. Description bidirectional logic level-shifting application[1]

| State | DIR CTRL | OE | I/O-1 | I/O-2 | Description |
|-------|----------|----|--------|--------|---|
| 1 | Н | L | output | input | system-1 data to system-2 |
| 2 | Н | Н | Z | Z | system-2 is getting ready to send data to system-1. I/O-1 and I/O-2 are disabled. The bus-line state depends on bus hold. |
| 3 | L | Н | Z | Z | DIR bit is set LOW. I/O-1 and I/O-2 still are disabled. The bus-line state depends on bus hold. |
| 4 | L | L | input | output | system-2 data to system-1 |

^[1] H = HIGH voltage level; L = LOW voltage level; Z = high-impedance OFF-state.

13.3 Power-up considerations

The device is designed such that no special power-up sequence is required other than GND being applied first.

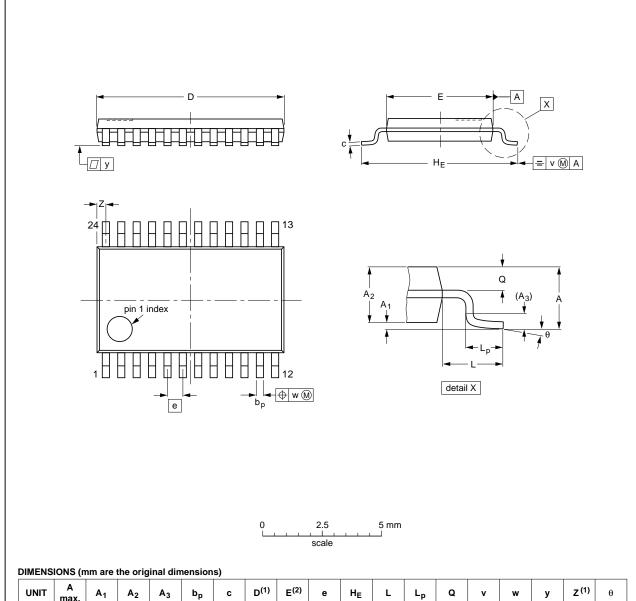
Table 17. Typical total supply current $(I_{CC(A)} + I_{CC(B)})$

| V _{CC(A)} | V _{CC(B)} | V _{CC(B)} | | | | | | | | |
|--------------------|--------------------|--------------------|-------|-------|-------|----|--|--|--|--|
| | 0 V | 1.8 V | 2.5 V | 3.3 V | 5.0 V | | | | | |
| 0 V | 0 | < 1 | < 1 | < 1 | < 1 | μΑ | | | | |
| 1.8 V | < 1 | < 2 | < 2 | < 2 | 2 | μΑ | | | | |
| 2.5 V | < 1 | < 2 | < 2 | < 2 | < 2 | μΑ | | | | |
| 3.3 V | < 1 | < 2 | < 2 | < 2 | < 2 | μΑ | | | | |
| 5.0 V | < 1 | 2 | < 2 | < 2 | < 2 | μΑ | | | | |

14. Package outline

TSSOP24: plastic thin shrink small outline package; 24 leads; body width 4.4 mm

SOT355-1



| UNIT | A max. | A ₁ | A ₂ | A ₃ | bp | C | D ⁽¹⁾ | E ⁽²⁾ | e | HE | L | Lp | Q | ٧ | w | у | Z ⁽¹⁾ | θ |
|------|-----------|----------------|----------------|----------------|--------------|------------|------------------|------------------|------|------------|---|--------------|------------|-----|------|-----|------------------|----------|
| mm | 1.1 | 0.15 0.05 | 0.95 0.80 | 0.25 | 0.30 0.19 | 0.2 0.1 | 7.9 7.7 | 4.5 4.3 | 0.65 | 6.6 6.2 | 1 | 0.75 0.50 | 0.4 0.3 | 0.2 | 0.13 | 0.1 | 0.5 0.2 | 8° 0° |

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

| OUTLINE | | REFER | ENCES | EUROPEAN | ISSUE DATE |
|----------|-----|--------|-------|------------|----------------------------------|
| VERSION | IEC | JEDEC | JEITA | PROJECTION | ISSUE DATE |
| SOT355-1 | | MO-153 | | | -99-12-27 03-02-19 |
| | | | | ' | |

Fig 16. Package outline SOT355-1 (TSSOP24)

DHVQFN24: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 24 terminals; body $3.5 \times 5.5 \times 0.85$ mm

SOT815-1

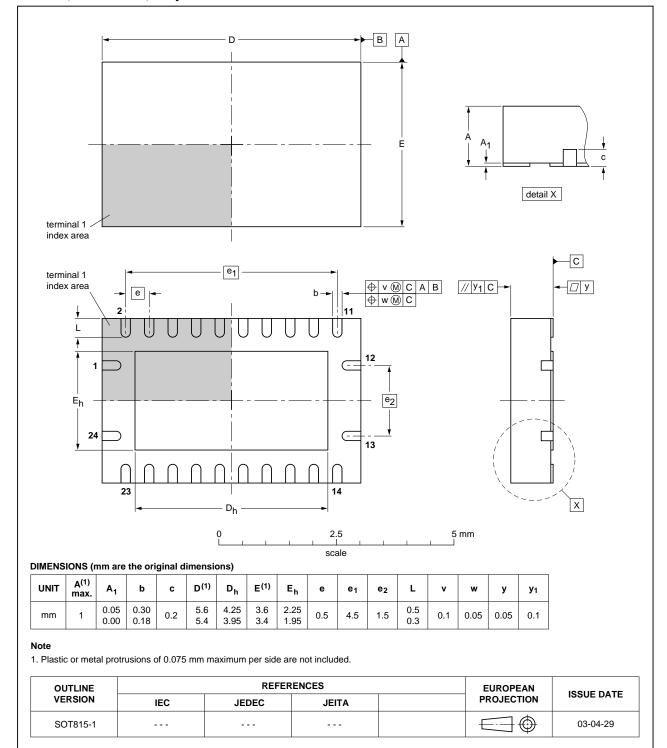


Fig 17. Package outline SOT815-1 (DHVQFN24)

15. Abbreviations

Table 18. Abbreviations

| Acronym | Description |
|---------|----------------------|
| CDM | Charged Device Model |
| DUT | Device Under Test |
| HBM | Human Body Model |
| MM | Machine Model |

16. Revision history

Table 19. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|---------------------|----------------------|--------------------|---------------|---------------------|
| 74LVC_LVCH8T245 v.3 | 20111212 | Product data sheet | - | 74LVC_LVCH8T245 v.2 |
| Modifications: | Legal pages updated. | | | |
| 74LVC_LVCH8T245 v.2 | 20110211 | Product data sheet | - | 74LVC_LVCH8T245 v.1 |
| 74LVC_LVCH8T245 v.1 | 20100111 | Product data sheet | - | - |

17. Legal information

17.1 Data sheet status

| Document status[1][2] | Product status[3] | Definition |
|--------------------------------|-------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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74LVC8T245; 74LVCH8T245

8-bit dual supply translating transceiver; 3-state

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